

Type number	Package	Package description	Total product weight
74AUP2G58GU	SOT1160-1	XQFN10	3.64519 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935304479115	6	1	260	30 s	1	240	20 s	3	Bangkok, Thailand; Suzhou, China; Nijmegen, Netherlands	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Adhesive	Additive	Non hazardous	Proprietary	0.00500	5.00000	0.13717
	Filler	Aluminium Trioxide (Al2O3)	1344-28-1	0.04000	40.00000	1.09734
	Polymer	Bisphenol-A Bisphenol-A Diglycidyl Ether copolymer	25036-25-3	0.01500	15.00000	0.41150
		Bisphenol-A/Epichlorohydrin Epoxy resin (generic)	25068-38-6	0.01000	10.00000	0.27433
		Resin system	Proprietary	0.03000	30.00000	0.82300
		subTotal		0.10000	100.00000	2.74334
Die	Doped silicon	Silicon (Si)	7440-21-3	0.09814	100.00000	2.69230
		subTotal		0.09814	100.00000	2.69230
Lead Frame Material	Copper alloy	Copper (Cu)	7440-50-8	0.67900	97.00000	18.62729
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.02100	3.00000	0.57610
		subTotal		0.70000	100.00000	19.20339
Mould Compound	Additive	Non hazardous	Proprietary	0.08242	3.17000	2.26106
	Filler	Silica fused	60676-86-0	2.19648	84.48000	60.25694
	Flame retardant	Magnesium Hydroxide (Mg(OH)2)	1309-42-8	0.09282	3.57000	2.54637
	Pigment	Carbon black	1333-86-4	0.00468	0.18000	0.12839
	Polymer	1,4-bis(methoxymethyl)benzene/phenol copolymer	26834-02-6	0.09100	3.50000	2.49644
		Epoxy resin system	Proprietary	0.09282	3.57000	2.54637
		Tetramethylbiphenyl diglycidyl ether	85954-11-6	0.03978	1.53000	1.09130
		subTotal		2.60000	100.00000	71.32687
Pre-Plating	Pure metal layer	Gold (Au)	7440-57-5	0.00100	1.00000	0.02743
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.09700	97.00000	2.66104
		Palladium (Pd)	7440-05-3	0.00200	2.00000	0.05487
		subTotal		0.10000	100.00000	2.74334
Wire	Pure metal	Gold (Au)	7440-57-5	0.04658	99.00000	1.27773
		Palladium (Pd)	7440-05-3	0.00047	1.00000	0.01291
		subTotal		0.04705	100.00000	1.29064

#### Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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